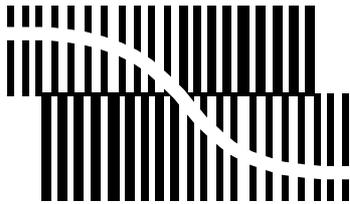


DATA SHEET



BITSTREAM CONVERSION

UDA1324TS

Ultra low-voltage stereo filter DAC

Preliminary specification
Supersedes data of 1998 Oct 02
File under Integrated Circuits, IC01

1999 Oct 12

Ultra low-voltage stereo filter DAC

UDA1324TS

FEATURES

General

- Low power consumption
- Ultra low power supply voltage 1.9 to 2.7 V
- Selectable control via L3 microcontroller interface or via static pin control.
- 256, 384 and 512 f_s system clock (f_{sys}), selectable via the L3 interface or 256 and 384 f_s clock mode via static pin control
- Supports sampling frequencies from 16 to 48 kHz.
- Integrated digital filter plus non inverting Digital-to-Analog Converter (DAC)
- No analog post filtering required for DAC
- Slave mode only applications
- Easy application
- Small package size (SSOP16).

Multiple format input interface

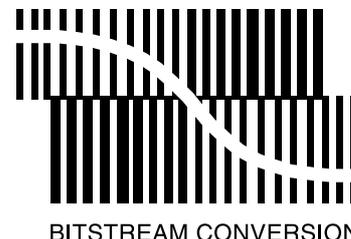
- I²S-bus, MSB-justified and LSB-justified 16, 18 and 20 bits format compatible (in L3-mode)
- I²S-bus and LSB-justified 16, 18 and 20 bits format compatible
- 1 f_s input format data rate.

DAC digital sound processing

- Digital logarithmic volume control via L3
- Digital de-emphasis for 32, 44.1 and 48 kHz f_s via L3 or 44.1 kHz f_s via static pin control
- Soft mute via static pin control or via L3 interface.

Advanced audio configuration

- Stereo line output (under L3 volume control)
- High linearity, wide dynamic range, low distortion.



APPLICATIONS

- Portable digital audio equipment, see Fig.8.

GENERAL DESCRIPTION

The UDA1324TS is a single-chip stereo DAC employing bitstream conversion techniques. The ultra low voltage requirements make the device eminently suitable for use in portable digital audio equipment which incorporates playback functions.

The UDA1324TS supports the I²S-bus data format with word lengths of up to 20 bits, the MSB-justified data format with word lengths of up to 20 bits and the LSB-justified serial data format with word lengths of 16, 18 and 20 bits.

The UDA1324TS can be used in two modes, either L3-mode or static pin mode.

In the L3-mode, all digital sound processing features must be controlled via the L3 interface, including the selection of the system clock setting.

In the two static-modes, the UDA1324TS can be operated in the 256 f_s and 384 f_s system clock mode. The mute, de-emphasis for 44.1 kHz and 4 digital input formats (I²S-bus, 16, 18 and 20 bits LSB formats) can be selected via static pins. The L3 interface cannot be used in this application mode, volume control is also not available in this mode.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
UDA1324TS	SSOP16	plastic shrink small outline package; 16 leads; body width 4.4 mm	SOT369-1

Ultra low-voltage stereo filter DAC

UDA1324TS

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supplies						
V_{DDA}	analog supply voltage		1.9	2.0	2.7	V
V_{DDD}	digital supply voltage		1.9	2.0	2.7	V
I_{DDA}	analog supply current for DAC	note 1	–	4.0	–	mA
I_{DDD}	digital supply current	note 1	–	1.5	–	mA
DAC; note 1						
$V_{o(rms)}$	output voltage (RMS value)	note 2	–	500	–	mV
(THD + N)/S	total harmonic distortion plus noise-to-signal ratio	at 0 dB	–	–83	–78	dB
		at –60 dB; A-weighted	–	–36	–	dB
S/N	signal-to-noise ratio	code = 0; A-weighted	–	97	–	dB
α_{cs}	channel separation		–	100	–	dB
T_{amb}	operating ambient temperature		–20	–	+70	°C

Notes

1. The analog performance figures and supply currents are given assuming a 2.0 V supply voltage.
2. The DAC output voltage scales linearly with the power supply voltage.

BLOCK DIAGRAM

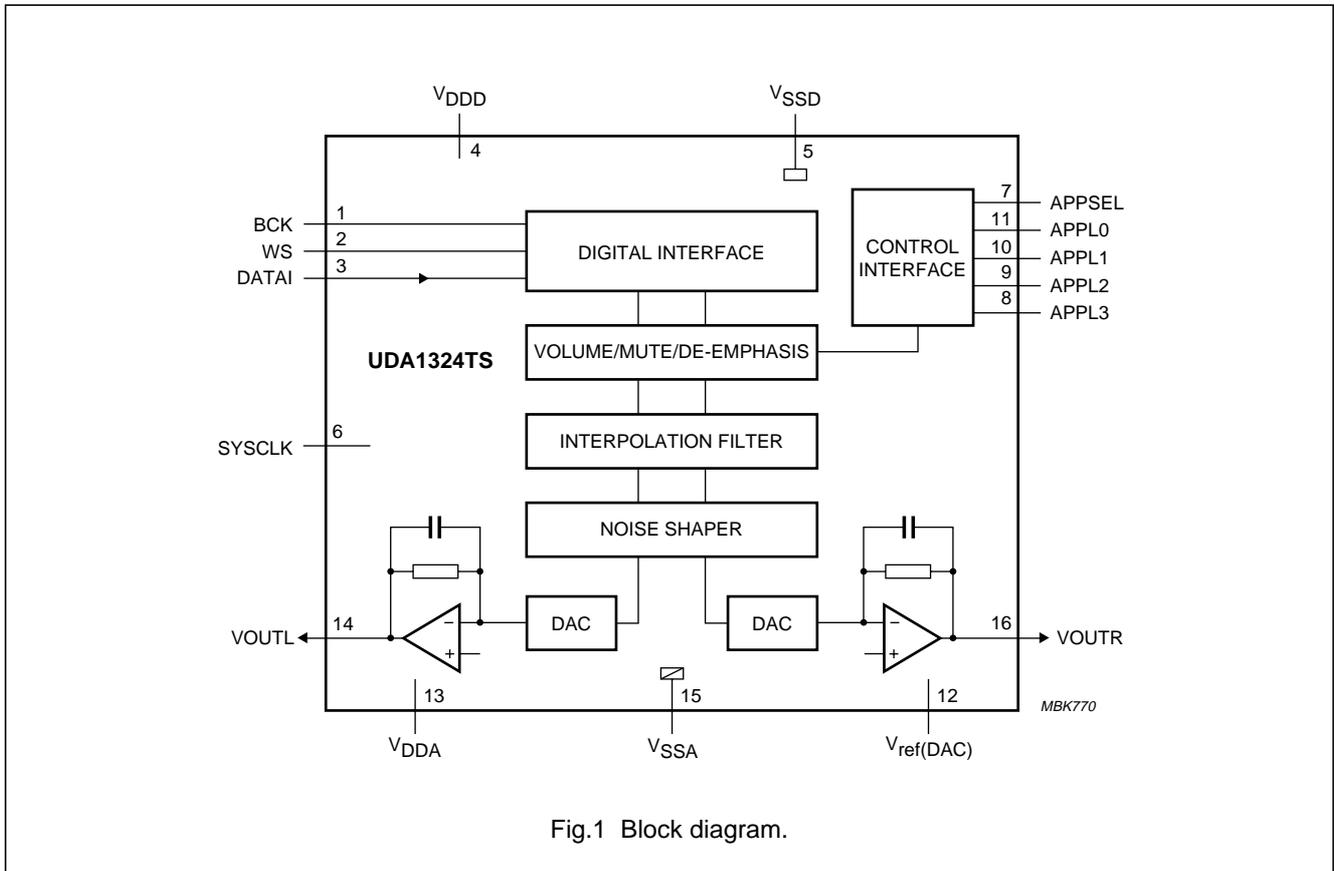


Fig.1 Block diagram.

Ultra low-voltage stereo filter DAC

UDA1324TS

PINNING

SYMBOL	PIN	DESCRIPTION
BCK	1	bit clock
WS	2	word select
DATAI	3	data input
V _{DDD}	4	digital power supply
V _{SSD}	5	digital ground
SYSCLK	6	system clock: 256, 384 and 512f _s
APPSEL	7	application mode select
APPL3	8	application pin 3
APPL2	9	application pin 2
APPL1	10	application pin 1
APPL0	11	application pin 0
V _{ref(DAC)}	12	DAC reference voltage
V _{DDA}	13	analog supply voltage
VOUTL	14	left channel output voltage
V _{SSA}	15	analog ground
VOUTR	16	right channel output voltage

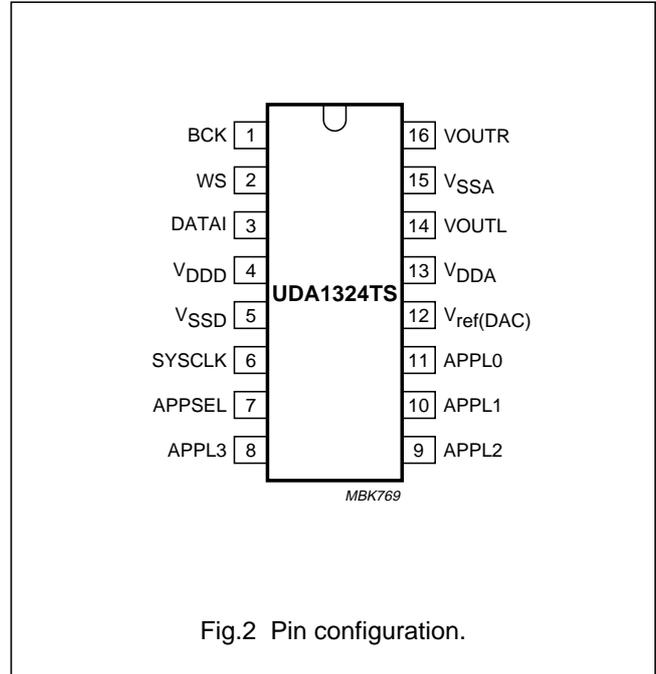


Fig.2 Pin configuration.

FUNCTIONAL DESCRIPTION

System clock

The UDA1324TS operates in slave mode only. In all applications, therefore, the system devices must provide the system clock. The system frequency is selectable and depends on the mode of operation.

The options are 256, 384 and 512f_s for the L3 mode and 256f_s plus 384f_s for the static mode. The system clock must be locked in frequency to the digital interface input signals.

The UDA1324TS supports sampling frequencies from 16 to 48 kHz.

Application modes

Operation can be set with the tri-value APPSEL pin, to L3 mode (APPSEL = V_{SSD}) or to either of two static modes (APPSEL = 0.5V_{DDD} or APPSEL = V_{DDD}). See Table 1 for APPL0 to APPL3 pin functions (active = HIGH).

Table 1 Selection modes via APPSEL

PIN	APPSEL		
	V _{SSD}	0.5V _{DDD} (384f _s)	V _{DDD} (256f _s)
APPL0	TEST	MUTE	MUTE
APPL1	L3CLK	DEEM	DEEM
APPL2	L3MODE	SF0	SF0
APPL3	L3DATA	SF1	SF1

For example, in the static pin control mode, the output signal can be soft muted by setting APPL0 HIGH. De-emphasis can be switched on for 44.1 kHz by setting APPL1 HIGH. APPL1 LOW will disable de-emphasis.

It should be noted that when the L3 interface is used, an L3 initialization must be performed when the IC is powered up. In the L3 mode, the APPL0 pin must be set LOW.

Ultra low-voltage stereo filter DAC

UDA1324TS

Multiple format input interface

L3 MODE:

- I²S-bus with data word length of up to 20 bits
- MSB-justified format with data word length up to 20 bits
- LSB-justified format with data word length of 16, 18 or 20 bits.

STATIC PIN MODE

The UDA1324TS supports the following data input name formats in the static pin mode (via SF0 and SF1):

- I²S-bus with data word length of up to 20 bits
- LSB-justified format with data word length of 16, 18 or 20 bits.

The static pin codes of the 4 formats, selectable via SF0 and SF1, is given in Table 2.

The UDA1324TS also accepts double speed data for double speed data monitoring purposes.

Table 2 Input format selection using SF0 and SF1

FORMAT	SF0	SF1
I ² S-bus	0	0
LSB-justified 16 bits	0	1
LSB-justified 18 bits	1	0
LSB-justified 20 bits	1	1

The formats are illustrated in Fig.3. Left and right data-channel words are time multiplexed. The WS signal must have 50% duty factor for all LSB-justified modes.

For BCK and WS hold times the BCK frequency must be equal or smaller then $64 \times WS$, or $f_{BCK} \leq 64f_{WS}$ in both L3 and static modes.

Interpolation filter (DAC)

The digital filter interpolates from 1 to $128f_s$ by cascading a recursive filter and a FIR filter, see Table 3.

Table 3 Interpolation filter characteristics

ITEM	CONDITION	VALUE (dB)
Pass-band ripple	0 to $0.45f_s$	± 0.1
Stop band	$>0.55f_s$	-50
Dynamic range	0 to $0.45f_s$	108

Noise shaper

The 3rd-order noise shaper operates at $128f_s$. It shifts in-band quantization noise to frequencies well above the audio band. This noise shaping technique enables high signal-to-noise ratios to be achieved. The noise shaper output is converted into an analog signal using a Filter-Stream DAC (FSDAC).

Filter-Stream DAC

The FSDAC is a semi-digital reconstruction filter that converts the 1-bit data stream of the noise shaper to an analog output voltage. The filter coefficients are implemented as current sources and are summed at virtual ground of the output operational amplifier. In this way very high signal-to-noise performance and low clock jitter sensitivity is achieved. A post-filter is not needed due to the inherent filter function of the DAC. On-board amplifiers convert the FSDAC output current to an output voltage signal capable of driving a line output.

The output voltage of the FSDAC scales linearly with the power supply voltage.

Ultra low-voltage stereo filter DAC

UDA1324TS

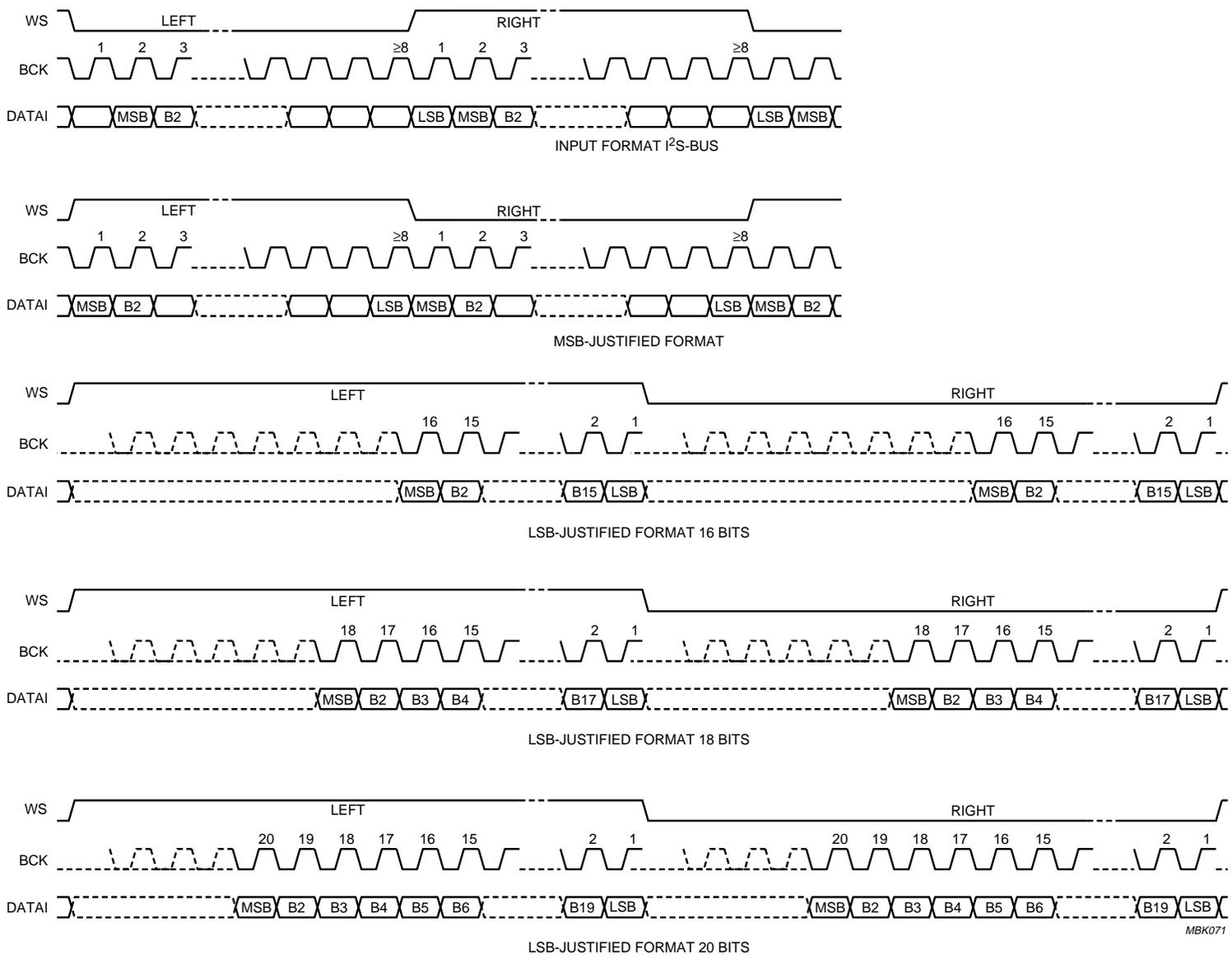


Fig.3 Serial interface; input format I²S-bus.

Ultra low-voltage stereo filter DAC

UDA1324TS

L3 INTERFACE DESCRIPTION

L3 interface description

The following system and digital sound processing features can be controlled in the microcontroller mode of the UDA1324TS:

- System clock frequency
- Data input format
- De-emphasis for 32, 44.1 and 48 kHz
- Volume
- Soft mute.

The exchange of data and control information between the microcontroller and the UDA1324TS is accomplished through a serial hardware interface comprising the following pins:

- L3DATA
- L3MODE
- L3CLOCK.

Information transfer through the microcontroller bus is organized in accordance with the L3 format, in which two different modes of operation can be distinguished; address mode and data transfer mode (see Figs 4 and 6).

The address mode is required to select a device communicating via the L3 bus and to define the destination registers for the data transfer mode.

Data transfer can only be in one direction, consisting of input to the UDA1324TS to program sound processing and other functional features.

Data bits 7 to 2 represent a 6-bit device address, bit 7 being the MSB. The address of the UDA1324TS is 000101 (bit 7 to bit 2). If the UDA1324TS receives a different address, it will deselect its microcontroller interface logic.

Data transfer mode

The selected address remains active during subsequent data transfers until the UDA1324TS receives a new address command. The fundamental timing of data transfers is essentially the same as in the address mode, see Fig.6. The maximum input clock and data rate is $64f_s$. All transfers are by 8-bit bytes. Data will be stored in the UDA1324TS after reception of a complete byte.

A multi-byte transfer is illustrated in Fig.5.

Table 4 Selection of data transfer

BIT 1	BIT 0	TRANSFER
0	0	DATA (volume, de-emphasis, mute)
0	1	not used
1	0	STATUS (system clock frequency, data input format)
1	1	not used

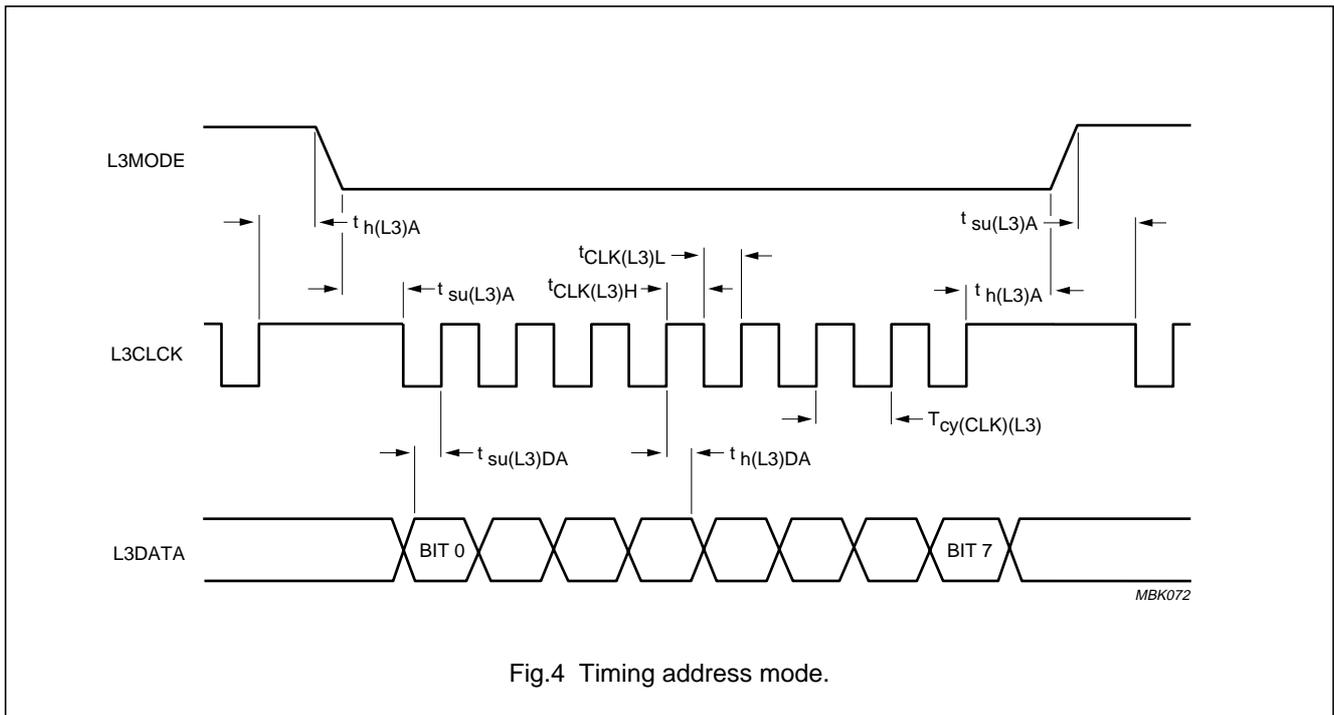
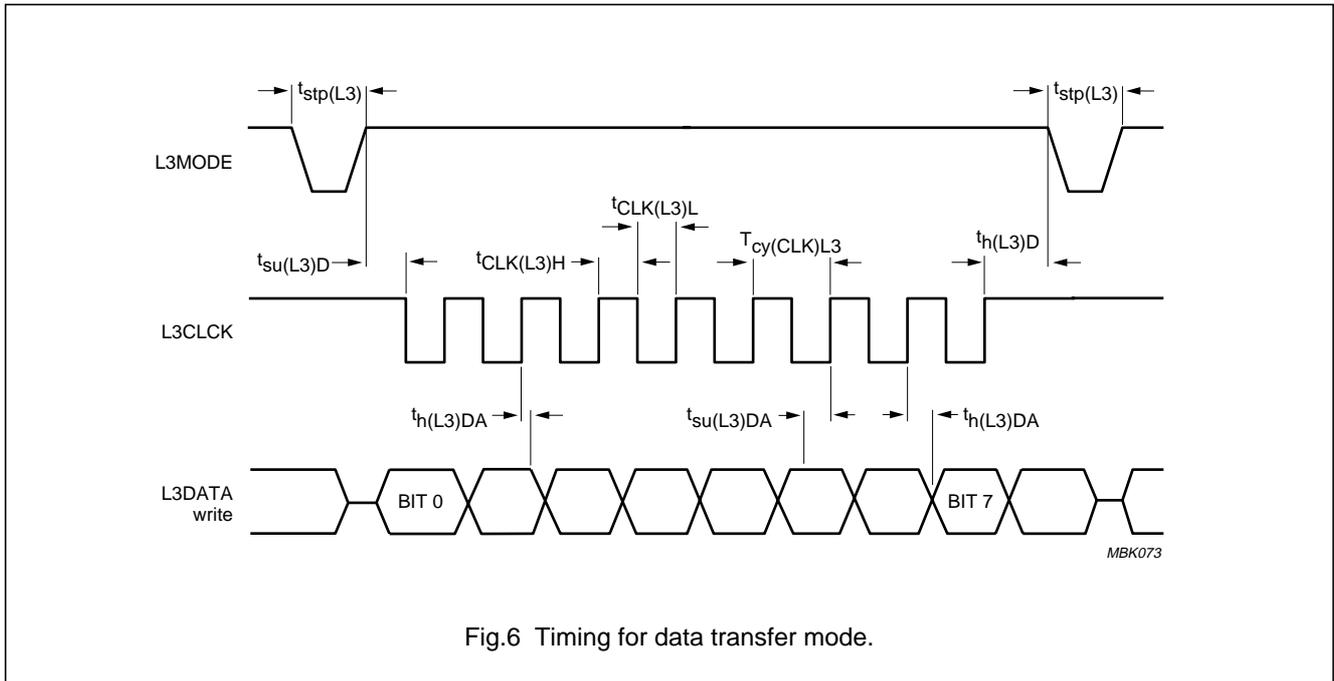
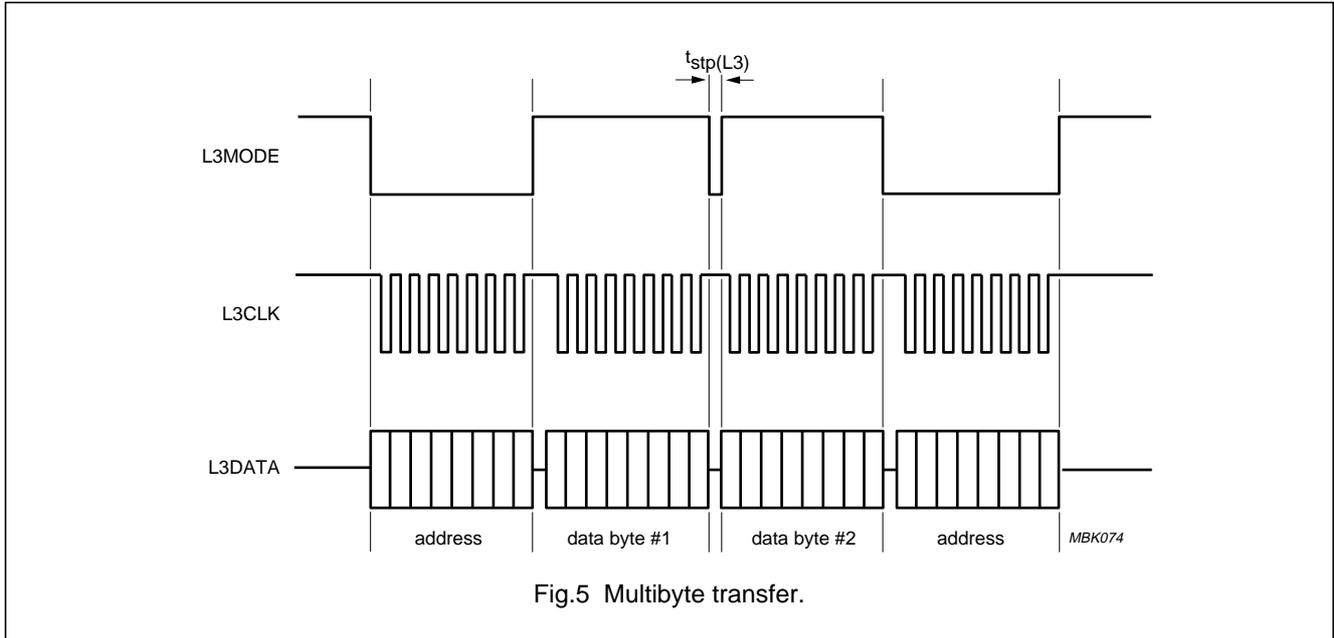


Fig.4 Timing address mode.

Ultra low-voltage stereo filter DAC

UDA1324TS



The sound processing and other feature values are stored in independent registers. The first selection of the registers is achieved by the choice of data type that is transferred. This is performed in the address mode, bit 1 and bit 0, see Table 4. The settings that can be controlled with 'STATUS' transfer are given in Table 5, and the settings that can be controlled using 'DATA' transfer are given in Table 6.

The second selection is performed by the 2 MSBs of the data byte (bit 7 and bit 6). The other bits in the data byte (bit 5 to bit 0) is the value that is placed in the selected registers.

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Table 5 Data transfer of type 'STATUS'

BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REGISTER SELECTED
0	0	SC1	SC0	IF2	IF1	IF0	0	System Clock frequency (1 : 0); data Input Format (2 : 0)
1	0	0	0	0	0	0	0	not used

Table 6 Data transfer of type 'DATA'

BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REGISTER SELECTED
0	0	VC5	VC4	VC3	VC2	VC1	VC0	Volume Control (5 : 0)
0	1	0	0	0	0	0	0	not used
1	0	0	DE1	DE0	MT	0	0	DE-emphasis (1 : 0); MuTe
1	1	0	0	0	0	0	1	default setting

Programming the features

When the data transfer of type 'STATUS' is selected, the features SYSTEM CLOCK FREQUENCY and DATA INPUT FORMAT can be controlled.

SYSTEM CLOCK FREQUENCY

The system clock frequency is a 2-bit value to select the external clock frequency.

Table 7 System clock settings

SC1	SC0	FUNCTION
0	0	512f _s
0	1	384f _s
1	0	256f _s
1	1	not used

DATA FORMAT

The data format is a 3-bit value to select the used data format.

Table 8 Data input format settings

IF2	IF1	IF0	FUNCTION
0	0	0	I ² S bus
0	0	1	LSB-justified, 16 bits
0	1	0	LSB -justified, 18 bits
0	1	1	LSB-justified, 20 bits
1	0	0	MSB-justified
1	0	1	not used
1	1	0	not used
1	1	1	not used

When the data transfer of type 'DATA' is selected, the features VOLUME, DE-EMPHASIS and MUTE can be controlled.

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UDA1324TS

VOLUME CONTROL

The volume control is a 6-bit value to program the volume attenuation (VC5 to VC0), 0 to $-\infty$ dB in steps of 1 dB.

Table 9 Volume settings

VC5	VC4	VC3	VC2	VC1	VC0	VOLUME (dB)
0	0	0	0	0	0	0
0	0	0	0	0	1	0
0	0	0	0	1	0	-1
0	0	0	0	1	1	-2
:	:	:	:	:	:	:
1	1	1	1	0	1	-60
1	1	1	1	1	1	$-\infty$

DE-EMPHASIS

De-emphasis is a 2-bit value to enable the digital de-emphasis filter.

Table 10 De-emphasis settings

DE1	DE0	FUNCTION
0	0	no de-emphasis
0	1	de-emphasis, 32 kHz
1	0	de-emphasis, 44.1 kHz
1	1	de-emphasis, 48 kHz

MUTE

Mute is a 1-bit value to enable the digital mute.

Table 11 Mute setting

MT	FUNCTION
0	no muting
1	muting

Ultra low-voltage stereo filter DAC

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{DDD}	digital supply voltage	note 1	–	5.0	V
V _{DDA}	analog supply voltage	note 1	–	5.0	V
T _{x_{tal}(max)}	maximum crystal temperature		–	150	°C
T _{stg}	storage temperature		–65	+125	°C
T _{amb}	operating ambient temperature		–20	+85	°C
V _{es}	electrostatic handling	note 2	–3000	+3000	V
		note 3	–300	+300	V

Notes

1. All supply connections must be made to the same power supply.
2. Equivalent to discharging a 100 pF capacitor via a 1.5 kΩ series resistor, except pin 14 which can withstand ESD pulses of –2500 V to +2500 V.
3. Equivalent to discharging a 200 pF capacitor via a 2.5 μH series inductor.

HANDLING

Inputs and outputs are protected against electrostatic discharge in normal handling. However, to be totally safe, it is desirable to take normal precautions appropriate to handling MOS devices.

QUALITY SPECIFICATION

In accordance with “SNW-FQ-611-E”.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	in free air	190	K/W

Ultra low-voltage stereo filter DAC

UDA1324TS

DC CHARACTERISTICS

$V_{DDD} = V_{DDA} = 2.0$ V; $T_{amb} = 25$ °C; $R_L = 5$ k Ω . All voltages referenced to ground (pins 5 and 15); unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP.	MAX	UNIT
Supplies						
V_{DDA}	DAC analog supply voltage	note 1	1.9	2.0	2.7	V
V_{DDD}	digital supply voltage	note 1	1.9	2.0	2.7	V
I_{DDA}	analog supply current	operation mode	–	4.0	–	mA
I_{DDD}	digital supply current	operation mode	–	1.5	–	mA
Digital input pins						
V_{IH}	HIGH-level input voltage		$0.8V_{DDD}$	–	–	V
V_{IL}	LOW-level input voltage		–	–	$0.2V_{DDD}$	V
$ I_{LI} $	input leakage current		–	–	1	μ A
C_i	input capacitance		–	–	10	pF
Three-level input pin (APPSEL)						
V_{IH}	HIGH-level input voltage		$0.8V_{DDD}$	–	$V_{DDD} + 0.5$	V
V_{IM}	MIDDLE-level input voltage		$0.3V_{DDD}$	–	$0.7V_{DDD}$	V
V_{IL}	LOW-level input voltage		–0.5	–	$0.2V_{DDD}$	V
DAC						
V_{ref}	reference voltage	referenced to V_{SSA}	$0.45V_{DDA}$	$0.5V_{DDA}$	$0.55V_{DDA}$	V
$I_{o(max)}$	maximum output current	(THD + N)/S < 0.1% $R_L = 5$ k Ω	–	0.16	–	mA
R_O	output resistance		–	0.15	2.0	Ω
R_L	load resistance		3	–	–	k Ω
C_L	load capacitance	note 2	–	–	50	pF

Notes

1. All supply connections must be made to the same external power supply unit.
2. When the DAC drives a capacitive load above 50 pF, a series resistance of 100 Ω must be used to prevent oscillations in the output operational amplifier.

Ultra low-voltage stereo filter DAC

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ANALOG CHARACTERISTICS

$V_{DD} = V_{DDA} = 2.0\text{ V}$; $f_i = 1\text{ kHz}$; $T_{amb} = 25\text{ °C}$; $R_L = 5\text{ k}\Omega$. All voltages referenced to ground (pins 5 and 15); unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
DAC					
$V_{o(rms)}$	output voltage (RMS value)		500	–	mV
ΔV_o	unbalance between channels		0.1	–	dB
(THD + N)/S	total harmonic distortion plus noise-to-signal ratio	at 0 dB	–83	–78	dB
		at –60 dB; A-weighted	–36	–	dB
S/N	signal-to-noise ratio	code = 0; A-weighted	97	–	dB
α_{cs}	channel separation		100	–	dB
PSRR	power supply ripple rejection ratio	$f_{ripple} = 1\text{ kHz}$; $V_{ripple} = 100\text{ mV (p-p)}$	50	–	dB

DIGITAL CHARACTERISTICS

$V_{DD} = V_{DDA} = 1.9\text{ to }2.7\text{ V}$; $T_{amb} = -20\text{ to }+85\text{ °C}$; $R_L = 5\text{ k}\Omega$. All voltages referenced to ground (pins 5 and 15); unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
T_{sys}	system clock cycle	$f_{sys} = 256f_s$	78	88	244	ns
		$f_{sys} = 384f_s$	52	59	162	ns
		$f_{sys} = 512f_s$	39	44	122	ns
t_{CWL}	LOW-level system clock pulse width	$f_{sys} < 19.2\text{ MHz}$	$0.3T_{sys}$	–	$0.7T_{sys}$	ns
		$f_{sys} \geq 19.2\text{ MHz}$	$0.4T_{sys}$	–	$0.6T_{sys}$	ns
t_{CWH}	HIGH-level system clock pulse width	$f_{sys} < 19.2\text{ MHz}$	$0.3T_{sys}$	–	$0.7T_{sys}$	ns
		$f_{sys} \geq 19.2\text{ MHz}$	$0.4T_{sys}$	–	$0.6T_{sys}$	ns
Serial input data timing (see Fig.7)						
$T_{cy(CLK)(bit)}$	bit clock period		300	–	–	ns
$t_{CLKH}(bit)$	bit clock HIGH time		100	–	–	ns
$t_{CLKL}(bit)$	bit clock LOW time		100	–	–	ns
t_r	rise time		–	–	20	ns
t_f	fall time		–	–	20	ns
$t_{su(i)(D)}$	data input set-up time		20	–	–	ns
$t_{h(i)(D)}$	data input hold time		0	–	–	ns
$t_{su}(WS)$	word selection set-up time		20	–	–	ns
$t_{h}(WS)$	word selection hold time		10	–	–	ns

Ultra low-voltage stereo filter DAC

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Microcontroller interface timing (see Figs 4 and 6)						
$T_{cy(CLK)(L3)}$	L3CLK cycle time		500	–	–	ns
$t_{CLK(L3)H}$	L3CLK HIGH period		250	–	–	ns
$t_{CLK(L3)L}$	L3CLK LOW period		250	–	–	ns
$t_{su(L3)A}$	L3MODE set-up time	addressing mode	190	–	–	ns
$t_{h(L3)A}$	L3MODE hold time	addressing mode	190	–	–	ns
$t_{su(L3)D}$	L3MODE set-up time	data transfer mode	190	–	–	ns
$t_{h(L3)D}$	L3MODE hold time	data transfer mode	190	–	–	ns
$t_{su(L3)DA}$	L3DATA set-up time	data transfer and addressing mode	190	–	–	ns
$t_{h(L3)DA}$	L3DATA hold time	data transfer and addressing mode	30	–	–	ns
$t_{stp(L3)}$	L3MODE halt time		190	–	–	ns

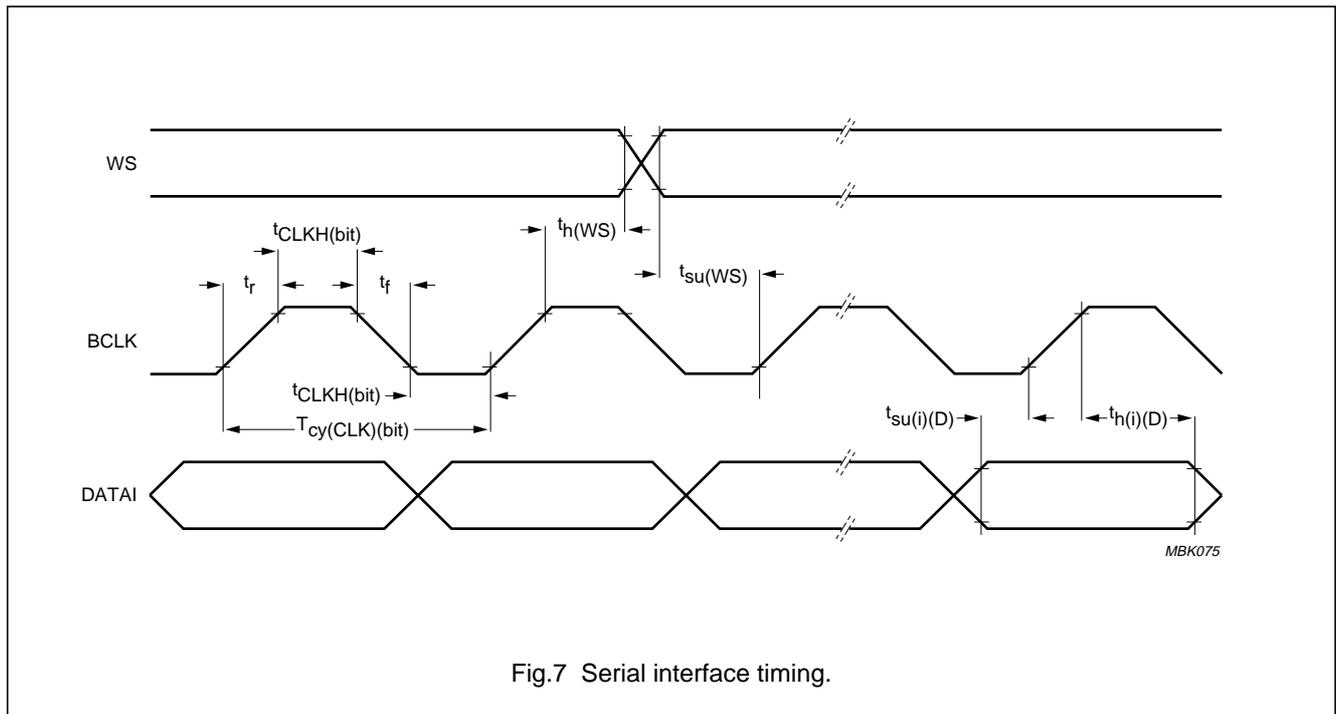


Fig.7 Serial interface timing.

Ultra low-voltage stereo filter DAC

UDA1324TS

APPLICATION INFORMATION

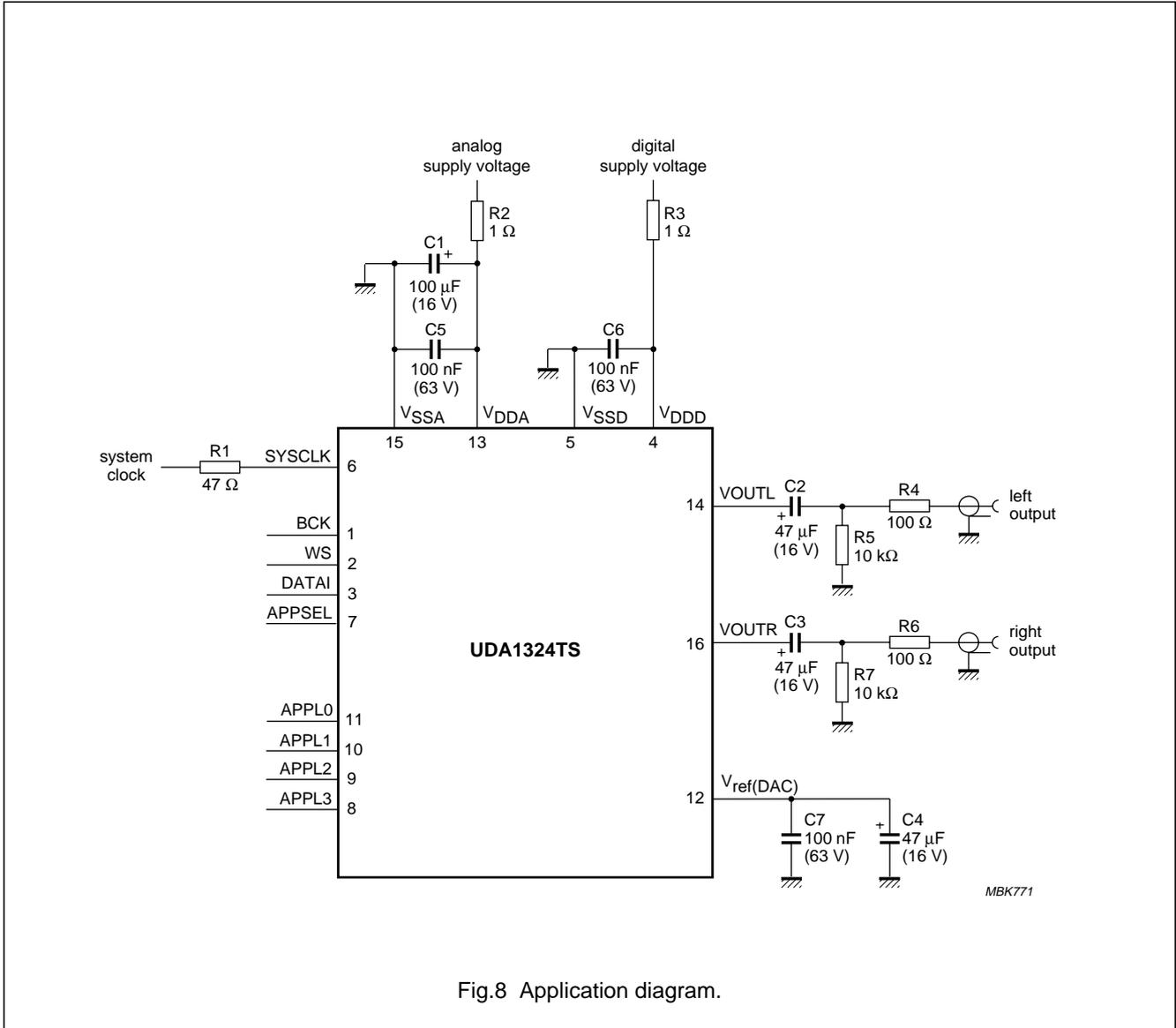


Fig.8 Application diagram.

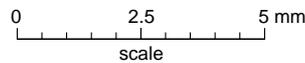
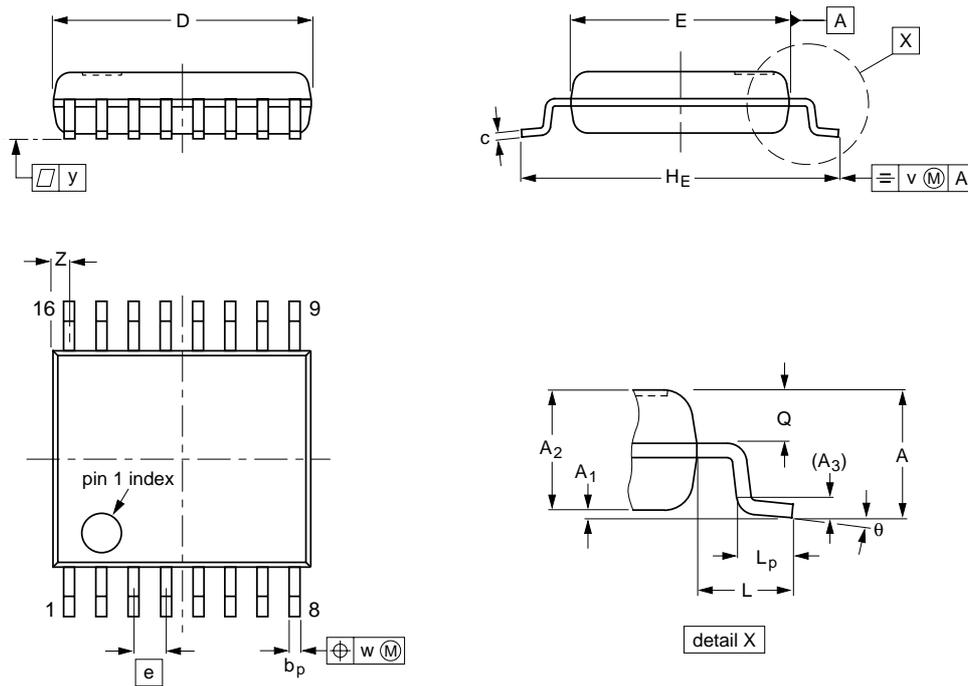
Ultra low-voltage stereo filter DAC

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PACKAGE OUTLINE

SSOP16: plastic shrink small outline package; 16 leads; body width 4.4 mm

SOT369-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	z ⁽¹⁾	θ
mm	1.5	0.15 0.00	1.4 1.2	0.25	0.32 0.20	0.25 0.13	5.30 5.10	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.45	0.65 0.45	0.2	0.13	0.1	0.48 0.18	10° 0°

Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT369-1						94-04-20 95-02-04

Ultra low-voltage stereo filter DAC

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SOLDERING

Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"Data Handbook IC26; Integrated Circuit Packages"* (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering is not always suitable for surface mount ICs, or for printed-circuit boards with high population densities. In these situations reflow soldering is often used.

Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, infrared/convection heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 250 °C. The top-surface temperature of the packages should preferably be kept below 230 °C.

Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
 - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
 - smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

Ultra low-voltage stereo filter DAC

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Suitability of surface mount IC packages for wave and reflow soldering methods

PACKAGE	SOLDERING METHOD	
	WAVE	REFLOW ⁽¹⁾
BGA, LFBGA, SQFP, TFBGA	not suitable	suitable
HBCC, HLQFP, HSQFP, HSOP, HTQFP, HTSSOP, SMS	not suitable ⁽²⁾	suitable
PLCC ⁽³⁾ , SO, SOJ	suitable	suitable
LQFP, QFP, TQFP	not recommended ⁽³⁾⁽⁴⁾	suitable
SSOP, TSSOP, VSO	not recommended ⁽⁵⁾	suitable

Notes

- All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the "Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods".
- These packages are not suitable for wave soldering as a solder joint between the printed-circuit board and heatsink (at bottom version) can not be achieved, and as solder may stick to the heatsink (on top version).
- If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
- Wave soldering is only suitable for LQFP, TQFP and QFP packages with a pitch (e) equal to or larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
- Wave soldering is only suitable for SSOP and TSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

Ultra low-voltage stereo filter DAC

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